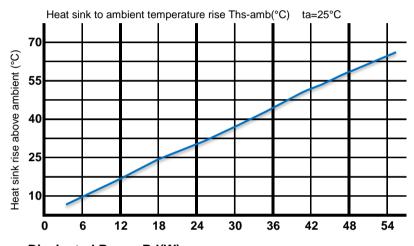


The thermal data table

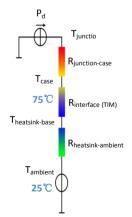
| Pd=Pe x (1-ηL) | | | Heat sink to ambient thermal resistance Rhs-amb(°C/W) | Heat sink to ambient temperature rise Ths-amb(°C) |
|------------------------|----------|----|-------------------------------------------------------------|---------------------------------------------------------|
| | | | Orbit-193 | |
| Dissipated Power Pd(W) | | 5 | 1.38 | 7.9 |
| | (| 15 | 1.13 | 20 |
| | - | 20 | 1.12 | 26.4 |
| | 3 | 30 | 1.05 | 37.6 |
| | ipated P | 40 | 1.02 | 48.7 |
| | | 45 | 1.01 | 54.6 |
| | 5 | 50 | 1.00 | 60 |
| | | 55 | 0.97 | 64.6 |



Dissipated Power Pd(W)

- st Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;
- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.
- Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- θ Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer
- shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the
- heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].
- *Thermal resistances outside the package $R_{\text{Interface (TIM)}}$ and $R_{\text{heatsink-ambient}}$ can be integrated into the thermal resistance $R_{\text{case-ambient}}$ at this point. Thus, the following formula is also used:
- $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$